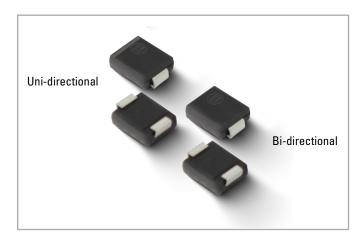
# 8.0SMDJ Series Surface Mount - 8000W









### **Additional Information**



Resources





### **Maximum Ratings and Thermal Characteristics**

(T<sub>A</sub>=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak Pulse Power Dissipation by 10/1000µs Waveform(Fig.1)(Note1)(Note2) -Single Die Parts	P <sub>PPM</sub>	8000	W
Power Dissipation on Infinite Heat Sink at $T_L \! = \! 50  ^{\circ}\!$	P <sub>D</sub>	6.5	W
Peak Forward Surge Current, 8.3ms Single Half Sine Wave (Note 3)	I <sub>FSM</sub>	300	А
Maximum Instantaneous Forward Voltage at 100A for Unidirectional Only	V <sub>F</sub>	5	V
Operating Temperature Range	TJ	-55 to 150	$^{\circ}$
Storage Temperature Range	T <sub>STG</sub>	-55 to 150	$^{\circ}$
Typical Thermal Resistance Junction to Lead	Rejl	15	°C/W
Typical Thermal Resistance Junction to Ambient	R <sub>OJA</sub>	75	°C/W

#### Notes:

- 1. Non-repetitive current pulse , per Fig.3 and derated above T<sub>J</sub> (initial) =25°C per Fig.2.
- 2. Mounted on copper pad area of 0.31x0.31" (8.0 x 8.0mm) to each terminal.
- 3. Measured on 8.3ms single half sine wave or equivalent square wave for unidirectional device only, duty cvcle=4 per minute maximum.

## **Description**

The 8.0SMDJ series is designed specifically to protect sensitive electronic equipment from voltage transients induced by lightning and other transient voltage events.

#### **Features**

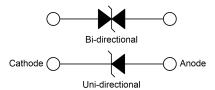
- 8000W peak pulse power capability at 10/1000µs waveform, repetition rate (duty cycles):0.01%
- Excellent clamping capability
- Low incremental surge resistance
- Typical I<sub>R</sub> less than 5µA when V<sub>B</sub> min>22V
- For surface mounted applications to optimize board space
- Low profile package
- Built-in strain relief
- Typical failure mode is short from over-specified voltage or current
- Whisker test is conducted based on JEDEC JESD201A per its table 4a and 4c
- ESD protection of data lines in accordance with IEC 61000-4-2, 30kV(Air), 30kV (Contact)
- EFT protection of data lines in accordance with IEC 61000-4-4

- Fast response time: typically less than 1.0ps from 0V to  $V_B$
- Compact size with high power density in DO-214AB Package
- Glass passivated chip junction
- High temperature to reflow soldering guaranteed: 260°C/20~40sec.
- V<sub>B</sub> @ T<sub>J</sub>= V<sub>B</sub>@25 °C x (1+ α Tx  $(T_{\perp}$  - 25)) (  $\alpha$  T:Temperature Coefficient, typical value is 0.1%)
- Meet MSL level1, per J-STD-020. LF maximum peak of 260℃
- Matte tin lead-free plated
- Halogen free and RoHS compliant
- Pb-free E3 means 2nd level interconnect is Pb-free and the terminal finish material is tin(Sn) (IPC/JEDEC J-STD-609A.01)

## **Applications**

TVS devices are ideal for the protection of I/O Interfaces,  $V_{\text{CC}}$  bus and other vulnerable circuits used in Telecom, Computer, Industrial and Consumer electronic applications.

#### **Functional Diagram**







# **Electrical Characteristics** ( $T_A$ =25 $^{\circ}$ C unless otherwise noted)

	Part Imber	Mar	/ice king de	Reverse Stand-Off Voltage	Vol	kdown Itage ®I <sub>T</sub>	Test Current	Maximum Clamping Voltage @I <sub>PP</sub>	Peak Pulse Current	Reverse Leakage @V <sub>R</sub>
Uni.	Bi.	Uni.	Bi.	V <sub>R</sub> (V)	V <sub>B MIn.</sub> (V)	V <sub>B Max.</sub> (V)	I⊤(mA)	V <sub>c</sub> (V)	I <sub>PP</sub> (A)	I <sub>R</sub> (μΑ)
8.0SMDJ22A	8.0SMDJ22CA	8PEX	8BEX	22.0	24.40	26.90	1	35.5	225.4	5
8.0SMDJ24A	8.0SMDJ24CA	8PEZ	8BEZ	24.0	26.70	29.50	1	38.9	205.7	5
8.0SMDJ26A	8.0SMDJ26CA	8PFE	8BFE	26.0	28.90	31.90	1	42.1	190.1	5
8.0SMDJ28A	8.0SMDJ28CA	8PFG	8BFG	28.0	31.10	34.40	1	45.4	176.2	5
8.0SMDJ30A	8.0SMDJ30CA	8PFK	8BFK	30.0	33.30	36.80	1	48.4	165.3	5
8.0SMDJ33A	8.0SMDJ33CA	8PFM	8BFM	33.0	36.70	40.60	1	53.3	150.1	5
8.0SMDJ36A	8.0SMDJ36CA	8PFP	8BFP	36.0	40.00	44.20	1	58.1	137.8	5
8.0SMDJ40A	8.0SMDJ40CA	8PFR	8BFR	40.0	44.40	49.10	1	64.5	124.2	5
8.0SMDJ43A	8.0SMDJ43CA	8PFT	8BFT	43.0	47.80	52.80	1	69.4	115.4	5
8.0SMDJ45A	8.0SMDJ45CA	8PFV	8BFV	45.0	50.00	55.30	1	72.7	110.1	5
8.0SMDJ48A	8.0SMDJ48CA	8PFX	8BFX	48.0	53.30	58.90	1	77.4	103.6	5
8.0SMDJ51A	8.0SMDJ51CA	8PFZ	8BFZ	51.0	56.70	62.70	1	82.4	97.0	5
8.0SMDJ54A	8.0SMDJ54CA	8PGE	8BGE	54.0	60.00	66.30	1	87.1	92.0	5
8.0SMDJ58A	8.0SMDJ58CA	8PGG	8BGG	58.0	64.40	71.20	1	93.6	85.6	5
8.0SMDJ60A	8.0SMDJ60CA	8PGK	8BGK	60.0	66.70	73.70	1	96.8	82.8	5
8.0SMDJ64A	8.0SMDJ64CA	8PGM	8BGM	64.0	71.10	78.60	1	103.0	77.8	5
8.0SMDJ70A	8.0SMDJ70CA	8PGP	8BGP	70.0	77.80	86.00	1	113.0	70.9	5
8.0SMDJ75A	8.0SMDJ75CA	8PGR	8BGR	75.0	83.30	92.10	1	121.0	66.3	5
8.0SMDJ78A	8.0SMDJ78CA	8PGT	8BGT	78.0	86.70	95.80	1	126.0	63.6	5
8.0SMDJ85A	8.0SMDJ85CA	8PGV	8BGV	85.0	94.40	104.00	1	137.0	58.4	5
8.0SMDJ90A	8.0SMDJ90CA	8PGX	8BGX	90.0	100.00	111.00	1	146.0	54.9	5
8.0SMDJ100A	8.0SMDJ100CA	8PGZ	8BGZ	100.0	111.00	123.00	1	162.0	49.4	5



## Ratings and Characteristic Curves (T<sub>A</sub>=25 ℃ unless otherwise noted)

Figure 1: Peak Pulse Power Rating Curve

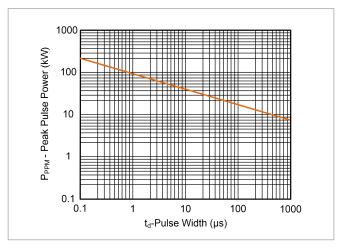
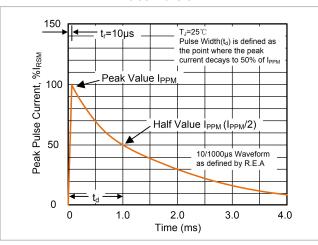


Figure 3:
Pulse Waveform



**Figure 5:**Steady State Power Dissipation Derating Curve

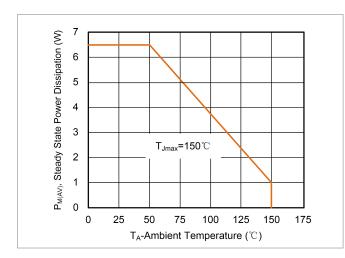


Figure 2: Pulse Derating Curve

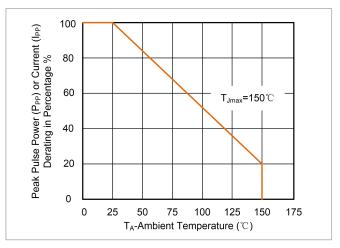


Figure 4:
Typical Junction Capacitance

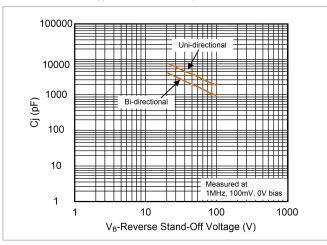
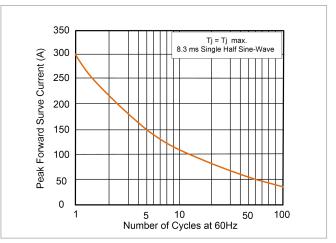


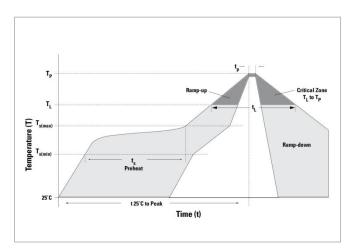
Figure 6: Maximum Non-Repetitive Forward Surge Current Uni-Directional





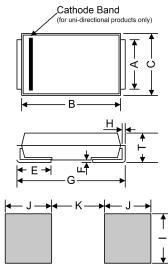
# **Soldering Parameters**

Reflow Conditi	Lead-free assembly	
Pre Heat	-Temperature Min (T <sub>S min</sub> )	150℃
	-Temperature Max (T <sub>S max</sub> )	200℃
	-Time (min to max) ( t <sub>s</sub> )	60 – 180 secs
Average ramp-	3°C/second max.	
T <sub>S (max)</sub> to T <sub>L</sub> -Rai	3°C/second max.	
Reflow	-Temperature (T <sub>L</sub> ) (Liquidus)	217℃
	-Time ( min to max) (t <sub>L</sub> )	60-150 seconds
Peak Temperat	260℃	
Time within 5°	20-40 seconds	
Ramp-down Ra	6°C/second max.	
Time 25℃ to Po	8 minutes max.	
Do not exceed	260℃	



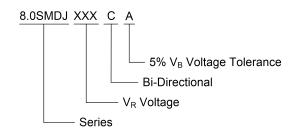
## **Dimensions**



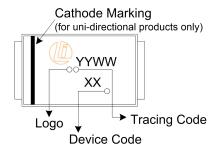


Symbol	Millime	ters	Inches		
	Min.	Max.	Min.	Max.	
A	2.900	3.200	0.114	0.126	
В	6.600	7.110	0.260	0.280	
С	5.590	6.220	0.220	0.245	
E	0.760	1.520	0.030	0.060	
F	-	0.203	-	0.008	
G	7.750	8.130	0.305	0.320	
Н	0.152	0.305	0.006	0.012	
Т	2.200	2.750	0.087	0.108	
I	3.300	-	0.129	-	
J	2.400	-	0.094	-	
K	-	4.200	-	0.165	

# **Part Numbering System**



# **Part Marking System**

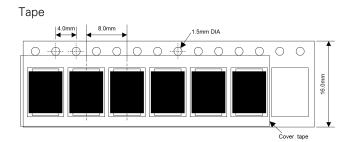




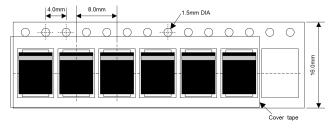
# **Packaging**

Part number	Component Package	Quantity	Packaging Option	Packaging Specification
8.0SMDJxxxXX	DO-214AB	3000	Tape & Reel - 16mm tape/13" reel	EIA STD RS-481

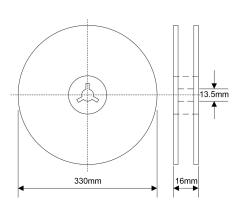
# **Tape and Reel Specification**



### For Uni-Devices



### 13 Inches Reel



Quantity: 3000pcs/reel

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